

January 17, 2019

Business Segment: ELECTRONICS

MACDERMID ALPHA TO PRESENT ON SMT MINIATURIZATION AT SMTA ROCKY MOUNTAIN EXPO

(Waterbury, CT USA) – The Assembly Solutions division of MacDermid Alpha Electronics Solutions, a global leader in the production of electronic soldering and bonding materials, will deliver a technical presentation and exhibit at the Rocky Mountain Expo & Tech Forum taking place in Denver, Colorado on Thursday, February 21, 2019.

Jason Fullerton, Customer Technical Support Engineer, will be present *The Continuing Miniaturization of SMT* during the Technical Forum. His presentation will focus on how the demand for smaller, more powerful electronics is influencing both materials and assembly technology, and the impact these devices are having on traditional SMT processes. “Ultra-fine pitch technology is an important part of device miniaturization,” said Mr. Fullerton. “Customers need to understand how these smaller, more powerful devices impact the traditional SMT processes, and what adjustments are required for process parameters and materials.”

In addition, MacDermid Alpha will be promoting its recently launched [ALPHA® OM-358](#) ultra-low voiding paste. ALPHA® OM-358 provides excellent resistance to electrochemical migration on fine pitch components, making it ideal for high reliability applications, such as Automotive, Medical and Defense. “This paste was designed to provide ultra-low voiding performance”, said Robert Wallace, Regional Marketing Manager for the Americas. “Providing less than ten percent voiding on bottom terminated components, this paste is well suited to meet the demands of our customers who have high reliability requirements”.

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